

Chiho Kim

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/9616921/publications.pdf>

Version: 2024-02-01

10
papers

186
citations

1478505

6
h-index

1372567

10
g-index

10
all docs

10
docs citations

10
times ranked

211
citing authors

#	ARTICLE	IF	CITATIONS
1	Boosting overall water splitting by incorporating sulfur into NiFe (oxy)hydroxide. Journal of Energy Chemistry, 2022, 64, 364-371.	12.9	68
2	Cyclic voltammetry studies of copper, tin and zinc electrodeposition in a citrate complex system for CZTS solar cell application. Current Applied Physics, 2016, 16, 207-210.	2.4	44
3	Effect of solder resist dissolution on the joint reliability of ENIG surface and Sn-Ag-Cu solder. Microelectronics Reliability, 2018, 87, 75-80.	1.7	24
4	Cobalt-Iron-Phosphate Hydrogen Evolution Reaction Electrocatalyst for Solar-Driven Alkaline Seawater Electrolyzer. Nanomaterials, 2021, 11, 2989.	4.1	14
5	Self-assembly of Ni-Fe layered double hydroxide at room temperature for oxygen evolution reaction. Energy Reports, 2020, 6, 248-254.	5.1	13
6	Promoting electrocatalytic overall water splitting by sulfur incorporation into CoFe-(oxy)hydroxide. Nanoscale Advances, 2021, 3, 6386-6394.	4.6	12
7	A comparative study of constant current control and adaptive control on electrode life time for resistance spot welding of galvanized steels. Journal of Welding and Joining, 2015, 33, 47-55.	1.3	4
8	A Comparative Study of Weldable Current Range on AC and MFDC Resistance Spot Welding for 440 MPa Grade Steel Sheet. Journal of Welding and Joining, 2017, 35, 34-42.	1.3	3
9	Boron behavior induced lamellar structure and anisotropic magnetic properties of Nd ₂ Fe ₁₄ B during HDDR process. Journal of the Korean Physical Society, 2017, 71, 130-133.	0.7	2
10	Characterization of the Contamination Factor of Electroless Ni Plating Solutions on the ENIG Process. Journal of Electronic Materials, 2018, 47, 5158-5164.	2.2	2